READ MODE

The DS1225AB and DS1225AD execute a read cycle whenever WE (Write Enable) is inactive (high) and $\overline{\text{CE}}$ (Chip Enable) and $\overline{\text{OE}}$ (Output Enable) are active (low). The unique address specified by the 13 address inputs (A₀ -A₁₂) defines which of the 8192 bytes of data is to be accessed. Valid data will be available to the eight data output drivers within t_{ACC} (Access Time) after the last address input signal is stable, providing that $\overline{\text{CE}}$ and $\overline{\text{OE}}$ access times are also satisfied. If $\overline{\text{CE}}$ and $\overline{\text{OE}}$ access times are not satisfied, then data access must be measured from the later-occurring signal and the limiting parameter is either t_{CO} for $\overline{\text{CE}}$ or t_{OE} for $\overline{\text{OE}}$ rather than address access.

WRITE MODE

The DS1225AB and DS1225AD execute a write cycle whenever the WE and CE signals are active (low) after address inputs are stable. The later-occurring falling edge of \overline{CE} or \overline{WE} will determine the start of the write cycle. The write cycle is terminated by the earlier rising edge of \overline{CE} or \overline{WE} . All address inputs must be kept valid throughout the write cycle. \overline{WE} must return to the high state for a minimum recovery time (t_{WR}) before another cycle can be initiated. The \overline{OE} control signal should be kept inactive (high) during write cycles to avoid bus contention. However, if the output drivers are enabled (\overline{CE} and \overline{OE} active) then \overline{WE} will disable the outputs in t_{ODW} from its falling edge.

DATA RETENTION MODE

The DS1225AB provides full functional capability for V_{CC} greater than 4.75 volts and write protects by 4.5 volts. The DS1225AD provides full-functional capability for V_{CC} greater than 4.5 volts and write protects by 4.25 volts. Data is maintained in the absence of V_{CC} without any additional support circuitry. The nonvolatile static RAMs constantly monitor V_{CC} . Should the supply voltage decay, the NV SRAMs automatically write protect themselves, all inputs become "don't care," and all outputs become high-impedance. As V_{CC} falls below approximately 3.0 volts, the power switching circuit connects the lithium energy source to RAM to retain data. During power-up, when V_{CC} rises above approximately 3.0 volts, the power switching circuit connects external V_{CC} to RAM and disconnects the lithium energy source. Normal RAM operation can resume after V_{CC} exceeds 4.75 volts for the DS1225AB and 4.5 volts for the DS1225AD.

FRESHNESS SEAL

Each DS1225 is shipped from Maxim with the lithium energy source disconnected, guaranteeing full energy capacity. When V_{CC} is first applied at a level of greater than V_{TP} , the lithium energy source is enabled for battery backup operation.

ABSOLUTE MAXIMUM RATINGS

Voltage on Any Pin Relative to Ground -0.3V to +6.0V

Operating Temperature

Commercial: 0° C to $+70^{\circ}$ C

Industrial: -40° C to $+85^{\circ}$ C -40°C to +85°C Storage Temperature

+260°C Lead Temperature (soldering, 10s)

Note: EDIP is wave or hand soldered only.

This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

(T_A: See Note 10)

| PARAMETER | SYMBOL | MIN | TYP | MAX | UNITS | NOTES |
|-------------------------------|-------------------|------|-----|----------|-------|-------|
| DS1225AB Power Supply Voltage | V_{CC} | 4.75 | 5.0 | 5.25 | V | |
| DS1225AD Power Supply Voltage | V_{CC} | 4.50 | 5.0 | 5.5 | V | |
| Logic 1 | V_{IH} | 2.2 | | V_{CC} | V | |
| Logic 0 | $V_{\rm IL}$ | 0.0 | | +0.8 | V | |

(T_A: See Note 10)

DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 5V \pm 5\% \text{ for DS1225AB})$ $(V_{CC} = 5V \pm 10\% \text{ for DS1225AD})$

| PARAMETER | SYMBOL | MIN | TYP | MAX | UNITS | NOTES |
|--|-------------------|------|------|------|--------|-------|
| Input Leakage Current | I_{IL} | -1.0 | | +1.0 | μΑ | |
| I/O Leakage Current | т | -1.0 | | +1.0 | 4 | |
| $\overline{\text{CE}} > V_{\text{IH}} < V_{\text{CC}}$ | I_{IO} | -1.0 | | +1.0 | μΑ | |
| Output Current @ 2.4V | I_{OH} | -1.0 | | | mA | |
| Output Current @ 0.4V | I_{OL} | 2.0 | | | mA | |
| Standby Current $\overline{\text{CE}} = 2.2\text{V}$ | I _{CCS1} | | 5.0 | 10.0 | mA | |
| Standby Current $\overline{CE} = V_{CC} - 0.5V$ | I_{CCS2} | | 3.0 | 5.0 | mA | |
| Operating Current | $I_{\rm CC01}$ | | | 75 | mA | |
| (Commercial) | 10001 | | | 73 | 1111/1 | |
| Operating Current | $I_{\rm CC01}$ | | | 85 | mA | |
| (Industrial) | 10001 | | | 05 | 1111 1 | |
| Write Protection Voltage | $ m V_{TP}$ | 4.50 | 4.62 | 4.75 | V | |
| (DS1225AB) | ▼ TP | 7.50 | 7.02 | 7.73 | Y | |
| Write Protection Voltage | V_{TP} | 4.25 | 4.37 | 4.5 | V | |
| (DS1225AD) | V TP | 4.23 | 4.37 | 4.3 | V | |

CAPACITANCE

 $(T_A = +25^{\circ}C)$

| _ <u>=</u> | | | | | \ /\ | / |
|--------------------------|------------------|-----|-----|-----|-------|-------|
| PARAMETER | SYMBOL | MIN | TYP | MAX | UNITS | NOTES |
| Input Capacitance | C _{IN} | | 5 | 10 | pF | |
| Input/Output Capacitance | C _{I/O} | | 5 | 10 | pF | |

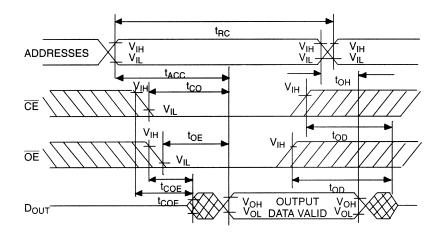
(T_A: See Note 10)

AC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 5V \pm 5\% \text{ for DS1225AB})$ $(V_{CC} = 5V \pm 10\% \text{ for DS1225AD})$

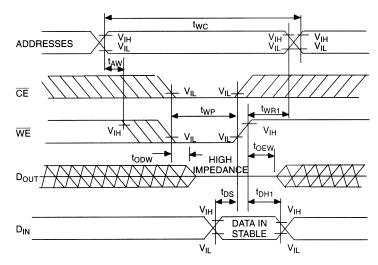
| | | DS1225AB-70 | | | |
|--------------------------------|--------------------|-------------|-------------|----|--------------|
| PARAMETER | SYMBOL | DS122 | DS1225AD-70 | | NOTES |
| | | MIN | MAX | | |
| Read Cycle Time | t_{RC} | 70 | | ns | |
| Access Time | t_{ACC} | | 70 | ns | |
| OE to Output Valid | t_{OE} | | 35 | ns | |
| CE to Output Valid | t_{CO} | | 70 | ns | |
| OE or CE to Output Active | $t_{\rm COE}$ | 5 | | ns | 5 |
| Output High Z from Deselection | t_{OD} | | 25 | ns | 5 |
| Output Hold from Address | t_{OH} | 5 | | ns | |
| Change | | | | | |
| Write Cycle Time | $t_{ m WC}$ | 70 | | ns | |
| Write Pulse Width | t_{WP} | 55 | | ns | 3 |
| Address Setup Time | $t_{ m AW}$ | 0 | | ns | |
| Write Recovery Time | t_{WR1} | 0 | | ns | 12 |
| Write Recovery Time | t_{WR2} | 10 | | ns | 13 |
| Output High Z from WE | t_{ODW} | | 25 | ns | 5 |
| Output Active from WE | t_{OEW} | 5 | | ns | 5 |
| Data Setup Time | $t_{ m DS}$ | 30 | | ns | 4 |
| Data Hold Time | t_{DH1} | 0 | | ns | 12 |
| Data Hold Tille | t_{DH2} | 10 | | ns | 13 |

READ CYCLE



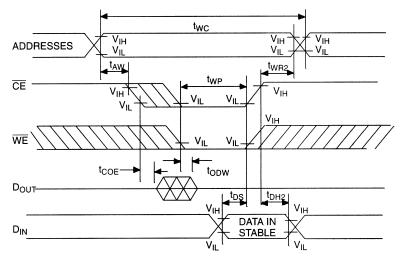
SEE NOTE 1

WRITE CYCLE 1



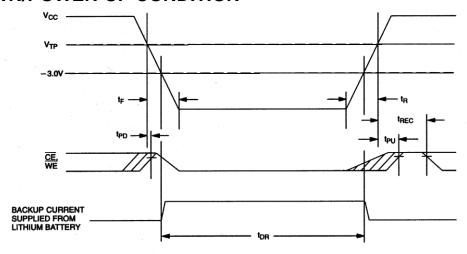
SEE NOTES 2, 3, 4, 6, 7, 8 AND 12

WRITE CYCLE 2



SEE NOTES 2, 3, 4, 6, 7, 8 AND 13

POWER-DOWN/POWER-UP CONDITION



SEE NOTE 11

POWER-DOWN/POWER-UP TIMING

(T_A: See Note 10)

| PARAMETER | SYMBOL | MIN | TYP | MAX | UNITS | NOTES |
|--|-------------------|-----|-----|-----|-------|-------|
| V_{CC} Fail Detect to \overline{CE} and \overline{WE} Inactive | t_{PD} | | | 1.5 | μs | 11 |
| V _{CC} slew from V _{TP} to 0V | t_{F} | 300 | | | μs | |
| V _{CC} slew from 0V to V _{TP} | t_R | 300 | | | μs | |
| V_{CC} Valid to \overline{CE} and \overline{WE} Inactive | t_{PU} | | | 2 | ms | |
| V _{CC} Valid to End of Write Protection | t_{REC} | | | 125 | ms | |

 $(T_A = +25^{\circ}C)$

| | | | | | ('A | - 0 0) |
|------------------------------|-----------------|-----|-----|-----|-------|--------------------|
| PARAMETER | SYMBOL | MIN | TYP | MAX | UNITS | NOTES |
| Expected Data Retention Time | t _{DR} | 10 | | | years | 9 |

WARNING:

Under no circumstance are negative undershoots, of any amplitude, allowed when device is in battery backup mode.

NOTES:

- 1. $\overline{\text{WE}}$ is high for a read cycle.
- 2. $\overline{OE} = V_{IH}$ or V_{IL} . If $\overline{OE} = V_{IH}$ during write cycle, the output buffers remain in a high-impedance state.
- 3. t_{WP} is specified as the logical AND of \overline{CE} and \overline{WE} . t_{WP} is measured from the latter of \overline{CE} or \overline{WE} going low to the earlier of \overline{CE} or \overline{WE} going high.
- 4. t_{DS} are measured from the earlier of \overline{CE} or \overline{WE} going high.
- 5. These parameters are sampled with a 5 pF load and are not 100% tested.
- 6. If the $\overline{\text{CE}}$ low transition occurs simultaneously with or later than the $\overline{\text{WE}}$ low transition, the output buffers remain in a high-impedance state during this period.
- 7. If the $\overline{\text{CE}}$ high transition occurs prior to or simultaneously with the $\overline{\text{WE}}$ high transition, the output buffers remain in a high-impedance state during this period.
- 8. If $\overline{\text{WE}}$ is low or the $\overline{\text{WE}}$ low transition occurs prior to or simultaneously with the $\overline{\text{CE}}$ low transition, the output buffers remain in a high-impedance state during this period.
- 9. Each DS1225AB and each DS1225AD has a built-in switch that disconnects the lithium source until V_{CC} is first applied by the user. The expected t_{DR} is defined as accumulative time in the absence of V_{CC} starting from the time power is first applied by the user. This parameter is guaranteed by design and is not 100% tested.
- 10. All AC and DC electrical characteristics are valid over the full operating temperature range. For commercial products, this range is 0°C to 70°C. For industrial products (IND), this range is -40°C to +85°C.
- 11. In a power down condition the voltage on any pin may not exceed the voltage on V_{CC} .
- 12. t_{WR1} , t_{DH1} are measured from \overline{WE} going high.
- 13. t_{WR2} , t_{DH2} are measured from \overline{CE} going high.
- 14. DS1225 modules are recognized by Underwriters Laboratories (UL) under file E99151.

DC TEST CONDITIONS

Outputs Open Cycle = 200ns for Operating Current All Voltages Are Referenced to Ground

AC TEST CONDITIONS

Output Load: 100 pF + 1TTL Gate
Input Pulse Levels: 0 - 3.0V
Timing Measurement Reference Levels

Input: 1.5V Output: 1.5V

Input Pulse Rise and Fall Times: 5ns

ORDERING INFORMATION

| PART | TEMP RANGE | SUPPLY TOLERANCE | PIN-PACKAGE | SPEED GRADE (ns) |
|-----------------|----------------------------------|---------------------|-------------|------------------|
| DS1225AB-70+ | 0°C to +70°C | $5V \pm 5\%$ | 28 720 EDIP | 70 |
| DS1225AB-70IND+ | -40°C to +85°C | 5V ± 5% | 28 720 EDIP | 70 |
| DS1225AD-70+ | 0° C to $+70^{\circ}$ C | 5V ± 10% | 28 720 EDIP | 70 |
| DS1225AD-70IND+ | -40°C to +85°C | 5V ± 10% | 28 720 EDIP | 70 |

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

PACKAGE INFORMATION

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

| PACKAGE TYPE | PACKAGE CODE | OUTLINE NO. | LAND PATTERN NO. |
|--------------|--------------|----------------|------------------|
| 28 EDIP | MDT28+2 | <u>21-0245</u> | _ |

REVISION HISTORY

| REVISION DATE | DESCRIPTION | PAGES CHANGED |
|------------------|--|------------------|
| 121907 | Added package information table; removed the DIP module package drawing and dimension table | 9 |
| 11/10 | Updated the storage information, soldering temperature, and lead temperature information in the <i>Absolute Maximum Ratings</i> section; removed the -85, -150, and -200 MIN/MAX information from the <i>AC Electrical Characteristics</i> table; updated the <i>Ordering Information</i> table (removed -85, -150, and -200 parts and leaded -70 parts) | 1, 3, 4, 8 |